

### **DATASHEET**

## ELUA2016OGB 1.8W Series



### **Features**

- Middle power UVA LED
- Dimension 2.04mm\*1.64mm\*0.75mm
- ESD protection
- · RoHS compliant
- Pb free

### **Description**

The ELUA2016 product series is a ceramic based LED with high quality and reliability that suitable for UV application

### **Applications**

- UV curing
- UV exposure
- UV catch mosquitoes



### **Product Nomenclature**

### ELUA2016OGB-PXXXXYY3040500-VD1M

EL = Everlight

UA = UVA

2016 = 2.0mm x 1.6mm Package

O = Package Material: Al<sub>2</sub>O<sub>3</sub>

G = Coating: Ag

B = Angle: 120°

P = Peak Wavelength

XXXX = Wavelength Range [1]

YY = Minimum Radiant Flux Spec [2]

3040 = Forward Voltage Spec: 3.0~4.0V

500 = Forward Current: 500mA

V = Chip Type: Vertical D = Chip Size: 45mil 1 = Chip QTY: 1 chip

M = Process Type: Molding

### Notes:

1. Wavelength Range

Symbol	Description
6070	360~370nm
8090	380~390nm
9000	390~400nm
0010	400~410nm

2. Minimum Radiant Flux Spec

Symbol	Description	
T5	500mW	
T7	600mW	



## **Absolute Maximum Ratings**

Parameter	Symbol	Ratings	Unit
Max. DC Forward Current (mA)	l <sub>F</sub>	500	mA
Max. ESD Resistance	V <sub>B</sub>	2000	V
Max. Junction Temperature	TJ	105	°C
Operating Temperature	T <sub>Opr</sub>	-40 ~ +60	°C
Storage Temperature	T <sub>Stg</sub>	-40 ~ +60	°C

### PN of the ELUA2016OGB series: UVA LEDs

UV, ELUA2016OGB series LEDs at 500mA are listed below

Order Code of ELUA2016OGB	Minimum Radiant Flux (mW)	Typical Radiant Flux (mW)	Maximum Radiant Flux (mW)	Peak Wavelength (nm)	Forward Voltage (V)	Forward Current (mA)
ELUA2016OGB-P6070T53040500-VD1M	500	800	1100	360~370	3.0~4.0	500
ELUA2016OGB-P8090T73040500-VD1M	600	850	1100	380~390	3.0~4.0	500
ELUA2016OGB-P9000T73040500-VD1M	600	850	1100	390~400	3.0~4.0	500
ELUA2016OGB-P0010T73040500-VD1M	600	850	1100	400~410	3.0~4.0	500



## **Product Binning Radiant Flux Bins**

365 Bin Code	Minimum Radiant Flux (mW)	Maximum Radiant Flux (mW)
T5	500	700
T6	700	900
T7	900	1100

385-405 Bin Code	Minimum Radiant Flux (mW)	Maximum Radiant Flux (mW)
Т7	600	800
Т8	800	1000
Т9	1000	1100

#### Notes:

- 1. Radiant flux measurement tolerance: ±10%.
- 2. Forward voltage bins are defined at I<sub>F</sub>=500mA operation.

### **Peak Wavelength Bins**

Group	Bin	Minimum Peak Wavelength (nm)	Maximum Peak Wavelength (nm)
	36	360	370
11	38	380	390
	39	390	400
	40	400	410

### Notes:

- 1. Peak Wavelength measurement tolerance: ±1nm.
- 2. Forward voltage bins are defined at I=500mA operation.

3.

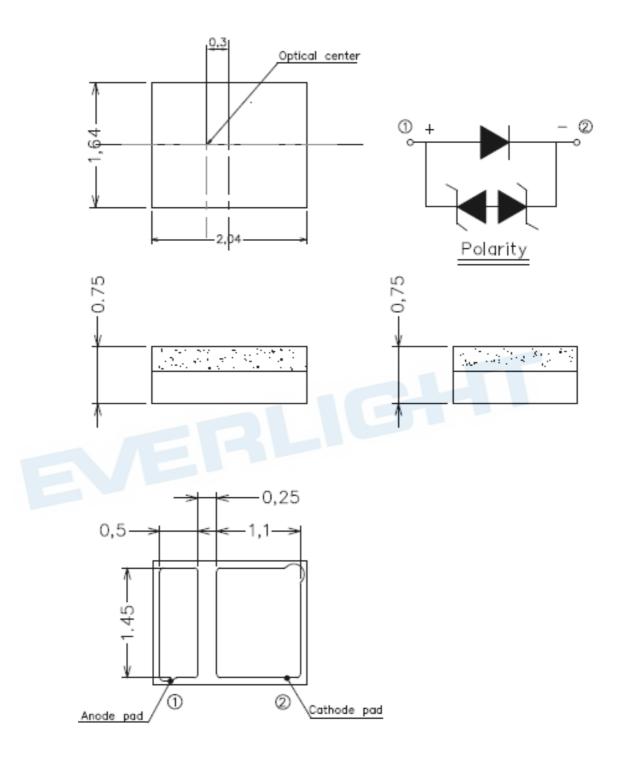
### **Forward Voltage Bins**

Bin	Minimum Forward Voltage (V)	Maximum Forward Voltage (V)
3032	3.0	3.2
3234	3.2	3.4
3436	3.4	3.6
3638	3.6	3.8
3840	3.8	4.0

#### Notes:

- 1. Forward voltage measurement tolerance: ±2%.
- 2. Forward voltage bins are defined at I<sub>F</sub>=500mA operation.

## **Mechanical Dimension**



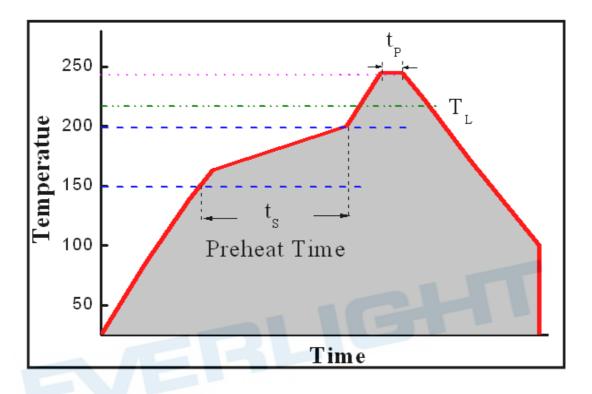
### Notes:

- Dimensions are in millimeters.
- Tolerances unless mentioned are ± 0.2mm.
- The thermal pad is electrically unity from the Cathode and contact pads.
- Do not handle the device by the lens. Incorrect force applied to the lens may lead to the failure of devices.

## **Reflow Soldering Characteristics**

#### For Reflow Process

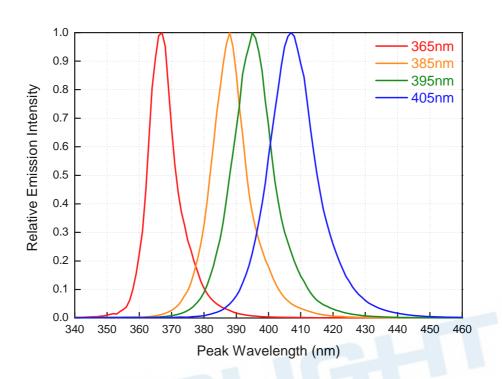
- a. ELUA series are suitable for SMT processes.
- b. Curing of glue in oven must be according to standard operation flow processes.



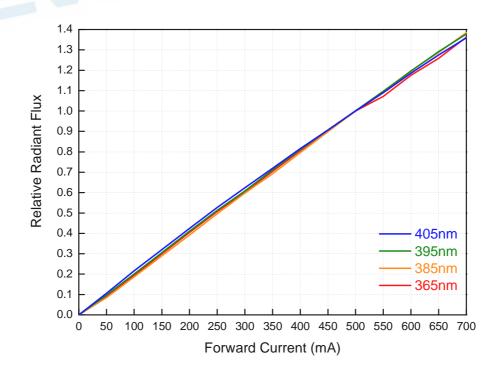
Profile Feature	Lead Free Assembly
Ramp-Up Rate	<b>2-3</b> ℃/S
Preheat Temperature	150-200 ℃
Preheat Time (t <sub>S</sub> )	<b>60-120</b> S
Liquid Temperature (T <sub>L</sub> )	<b>217</b> ℃
Time maintained above T <sub>L</sub>	<b>60-90</b> S
Peak Temperature (T <sub>P</sub> )	<b>240</b> ±5 ℃
Peak Time (t <sub>P</sub> )	Max <b>20</b> S
Ramp-Down Rate	<b>3-5</b> ℃/S

- c. Reflow soldering should not be done more than twice.
- d. In soldering process, stress on the LEDs during heating should be avoided.
- e. After soldering, do not bend the circuit board.

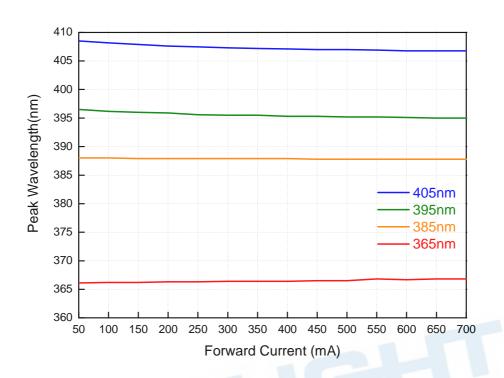
# Typical Characteristics Curves Spectrum @ Thermal Pad Temperature = 25℃



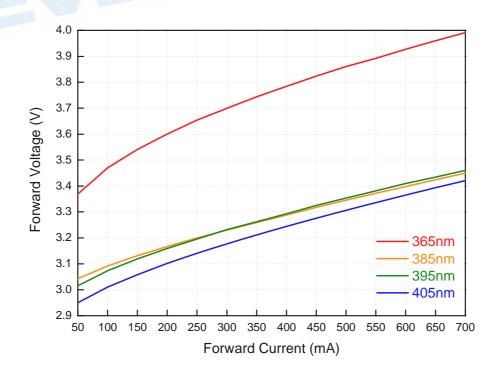
## Relative Radiant Flux vs. Forward Current @ Thermal Pad Temperature = 25°C



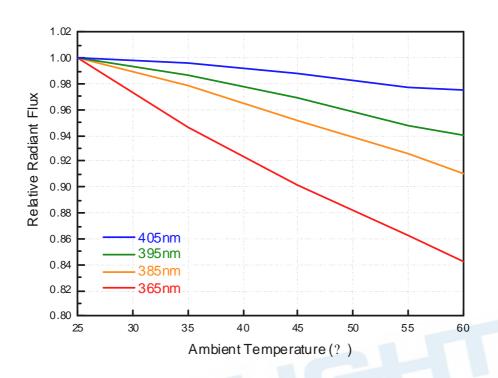
## Peak Wavelength vs. Forward Current @ Thermal Pad Temperature = 25°C



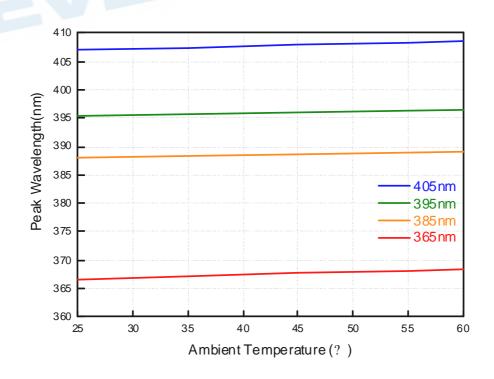
## Forward Voltage vs. Forward Current @ Thermal Pad Temperature = 25℃



## Relative Radiant Flux vs. Ambient Temperature @ Forward Current = 500mA

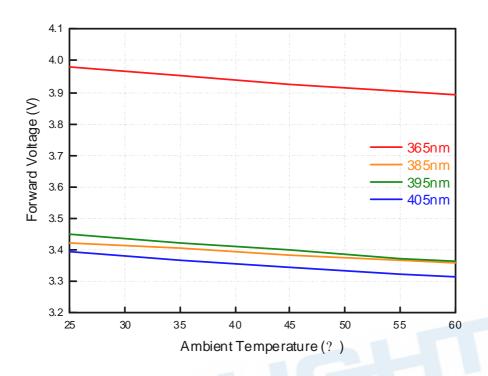


## Peak Wavelength vs. Ambient Temperature @ Forward Current = 500mA

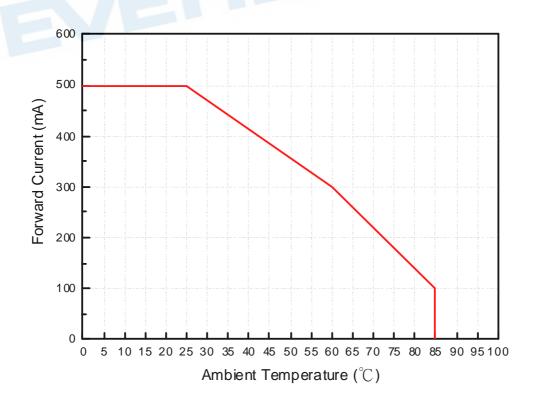




### Forward Voltage vs. Ambient Temperature @ Forward Current = 500mA

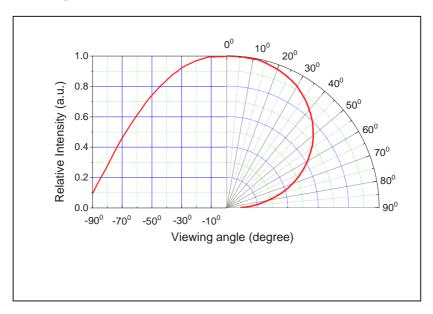


## **Derating Curve**





# **Typical Radiation Patterns Typical Diagram Characteristics of Radiation for ELUA2016**



#### Notes:

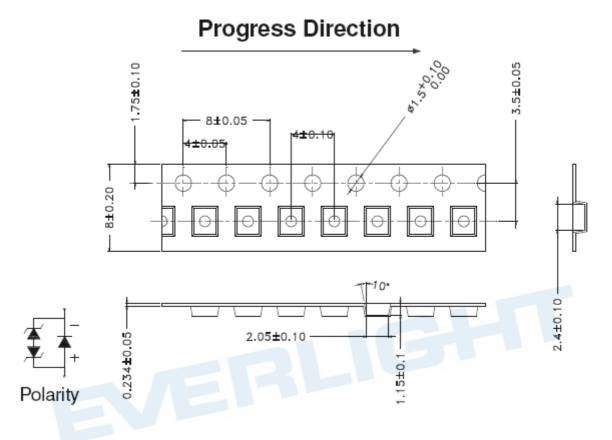
- 1.  $2\theta_{1/2}$  is the off axis angle from lamp centerline where the luminous intensity is 1/2 of the peak value.
- 2. View angle tolerance is  $\pm 5^{\circ}$ .



### **Emitter Tape Packaging**

### **Carrier Tape Dimensions as the following:**

Reel: 2000pcs

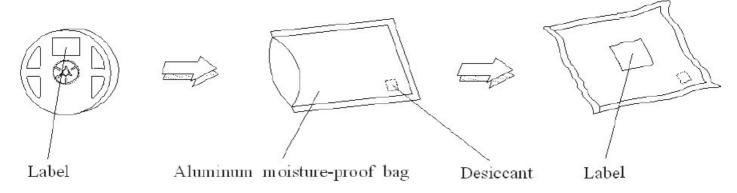


### Unit = mm

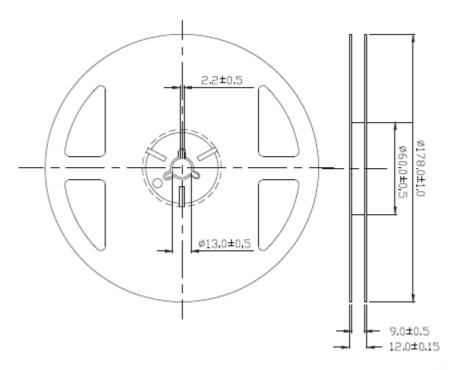
#### Notes:

- 1. Tolerance unless mentioned is ±0.1mm;
- 2. Packing amount is 500/1000/1500/2000 pcs per reel

### **Moisture Resistant Packaging**



### **Emitter Reel Dimensions**



#### Notes:

- Dimensions are in millimeters.
- Tolerances unless mentioned are ±0.1mm.

### **Product Labeling**

### **Label Explanation**

CPN: Customer Specification (when required)

P/N: Everlight Production Number

QTY: Packing Quantity

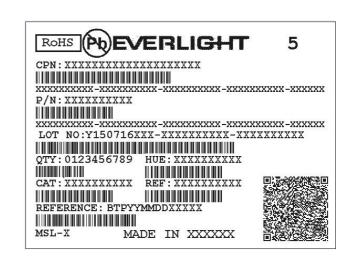
CAT: Luminous Flux (Brightness) Bin

HUE: Color Bin

REF: Forward Voltage Bin

LOT No: Lot Number

MADE IN TAIWAN: Production Place





### **Storage Conditions**

- Before the package is opened. The LEDs should be stored at 30°C or less and 90%RH or less after being shipped from EVERLIGHT and the storage life limits are 12 months.
- After opening the package: The LED's floor life is 1 year under 30°C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
- If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions. Baking treatment: 60±5°C for 24 hours.

### DISCLAIMER

- EVERLIGHT reserves the right(s) on the adjustment of product material mix for the specification.
- The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
- The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
- When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from the use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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- The product is not suitable for use in an ammonia environment.